

COMPOSITE RESIN COMPOSITION FOR ELECTRONIC COMPONENT AND
ELECTRONIC COMPONENT MOLDED FROM COMPOSITE RESIN COMPOSITION

ABSTRACT

The objective of the present invention is to provide a composite resin composition for an electronic component having excellent fluidity and an electronic component molded from the composite resin composition. The present invention provides a composite resin composition for an electronic component, the composition comprising a liquid crystal polymer (A), a milled fiber (B), and a plate-like inorganic filler (C); wherein the liquid crystal polymer (A) includes a constitutional unit (I) derived from 4-hydroxybenzoic acid, a constitutional unit (II) derived from 2-hydroxy-6-naphthoic acid, a constitutional unit (III) derived from terephthalic acid, a constitutional unit (IV) derived from isophthalic acid, and constitutional unit (V) derived from 4,4'-dihydroxybiphenyl, as essential components.

(FIG. 1)